

**Three Phase
Full Controlled Bridges**

PSDT 70

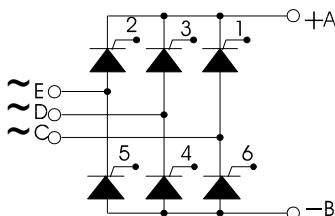
**I_{dAV}
V_{RRM}**

**= 70 A
= 400-1600 V**

Preliminary Data Sheet

V _{RSM} V _{DSM}	V _{RRM} V _{DRM}	Type
500	400	PSDT 70/04
900	800	PSDT 70/08
1300	1200	PSDT 70/12
1500	1400	PSDT 70/14
*1700	*1600	PSDT 70/16

* Delivery on request



Symbol	Test Conditions	Maximum Ratings		
I _{dAV}	T _C = 85 °C per module	70	A	
I _{TSM}	T _{VJ} = 45°C t = 10 ms (50 Hz), sine	550	A	
	V _R = 0 t = 8.3 ms (60 Hz), sine	600	A	
	T _{VJ} = T _{VJM} t = 10 ms (50 Hz), sine	500	A	
	V _R = 0 t = 8.3 ms (60 Hz), sine	550	A	
∫ i ² dt	T _{VJ} = 45°C t = 10 ms (50 Hz), sine	1520	A ² s	
	V _R = 0 t = 8.3 ms (60 Hz), sine	1520	A ² s	
	T _{VJ} = T _{VJM} t = 10 ms (50 Hz), sine	1250	A ² s	
	V _R = 0 t = 8.3 ms (60 Hz), sine	1250	A ² s	
(di/dt) _{cr}	T _{VJ} = T _{VJM} repetitive, I _T = 50 A	150	A/µs	
	f = 50Hz, t _p = 200µs			
	V _D = 2/3 V _{DRM}			
	I _G = 0.3 A non repetitive, I _T = 1/2 · I _{dAV}	500	A/µs	
	di _G /dt = 0.3 A/µs			
(dv/dt) _{cr}	T _{VJ} = T _{VJM} V _{DR} = 2/3 V _{DRM}	1000	V/µs	
	R _{GK} = ∞, method 1 (linear voltage rise)			
P _{GM}	T _{VJ} = T _{VJM} t _p = 30µs	≤ 10	W	
	I _T = I _{TAVM} t _p = 500µs	≤ 5	W	
P _{GAVM}		0.5	W	
V _{RGM}		10	V	
T _{VJ}		-40 ... + 125	°C	
T _{VJM}		125	°C	
T _{stg}		-40 ... + 125	°C	
V _{ISOL}	50/60 HZ, RMS t = 1 min	2500	V ~	
	I _{ISOL} ≤ 1 mA t = 1 s	3000	V ~	
M _d	Mounting torque (M5)	2 - 2.5	Nm	
Weight	typ.	100	g	

Features

- Package with fast-on terminals
- Isolation voltage 3000 V~
- Planar glasspassivated chips
- Low forward voltage drop
- UL registered E 148688

Applications

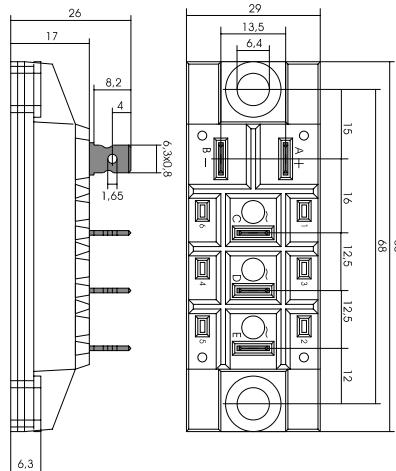
- Heat and temperature control for industrial furnaces and chemical processes
- Lighting control
- Motor control
- Power converter

Advantages

- Easy to mount with two screws
- Space and weight savings
- Improved temperature and power cycling capability
- High power density

Package, style and outline

Dimensions in mm (1mm = 0.0394")



Symbol	Test Conditions		Characteristic Value		
I_D, I_R	$T_{VJ} = T_{VJM}$, $V_R = V_{RRM}$, $V_D = V_{DRM}$		\leq	5	mA
V_T	$I_T = 80A$, $T_{VJ} = 25^\circ C$		\leq	1.64	V
V_{TO}	For power-loss calculations only ($T_{VJ} = T_{VJM}$)			0.85	V
r_T				11	$m\Omega$
V_{GT}	$V_D = 6V$	$T_{VJ} = 25^\circ C$	\leq	1.5	V
		$T_{VJ} = -40^\circ C$	\leq	1.6	V
I_{GT}	$V_D = 6V$	$T_{VJ} = 25^\circ C$	\leq	100	mA
		$T_{VJ} = -40^\circ C$	\leq	200	mA
V_{GD}	$T_{VJ} = T_{VJM}$	$V_D = 2/3 V_{DRM}$	\leq	0.2	V
I_{GD}	$T_{VJ} = T_{VJM}$	$V_D = 2/3 V_{DRM}$	\leq	5	mA
I_L	$T_{VJ} = 25^\circ C$, $t_P = 10\mu s$ $I_G = 0.45A$, $dI_G/dt = 0.45A/\mu s$		\leq	450	mA
I_H	$T_{VJ} = 25^\circ C$, $V_D = 6V$, $R_{GK} = \infty$		\leq	200	mA
t_{gd}	$T_{VJ} = 25^\circ C$, $V_D = 1/2 V_{DRM}$ $I_G = 0.45A$, $dI_G/dt = 0.45A/\mu s$		\leq	2	μs
t_q	$T_{VJ} = T_{VJM}$, $I_T = 20A$, $t_P = 200\mu s$, $V_R = 100V$ $-di/dt = 10A/\mu s$, $dv/dt = 15V/\mu s$, $V_D = 2/3 V_{DRM}$			250	μs
R_{thJC}	per thyristor; sine 180°el			0.9	K/W
	per module			0.15	K/W
R_{thJK}	per thyristor; sine 180° el			1.1	K/W
	per module			0.183	K/W
d_s	Creeping distance on surface			16.0	mm
d_A	Creeping distance in air			7.6	mm
a	Max. allowable acceleration			50	m/s^2

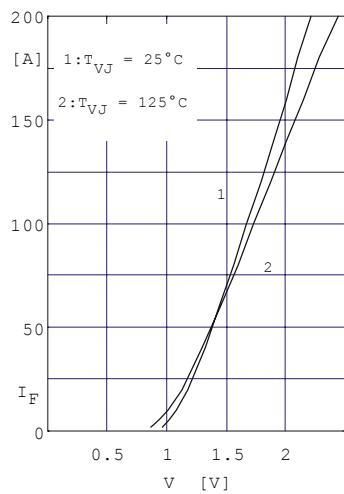


Fig. 1 Forward current vs. voltage drop per diode or thyristor

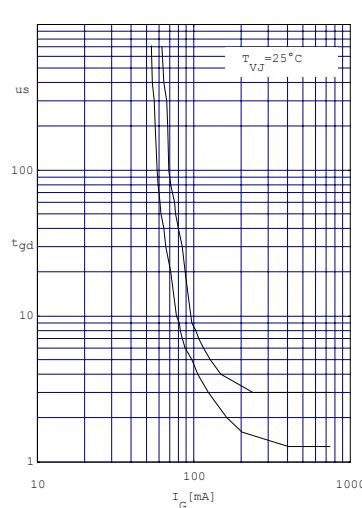


Fig. 2 Gate trigger delay time

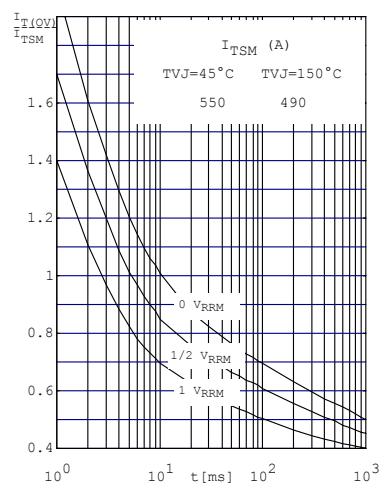


Fig. 3 Surge overload current per diode (or thyristor) I_{FSM} , I_{TSM} : Crest value t: duration

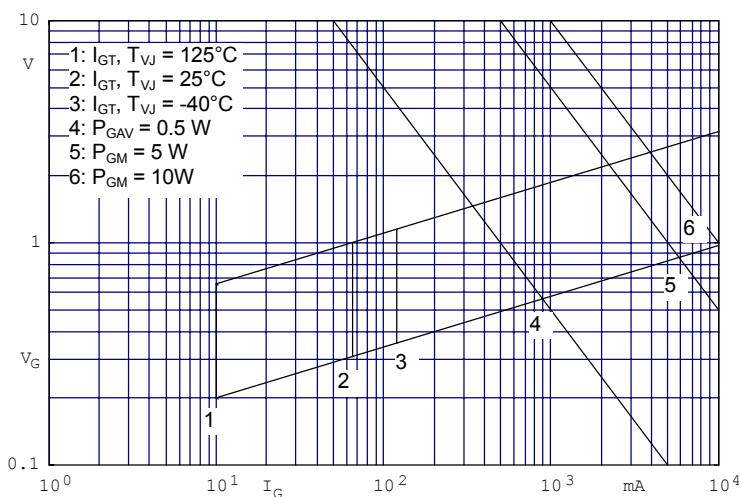


Fig.4 Gate trigger characteristic

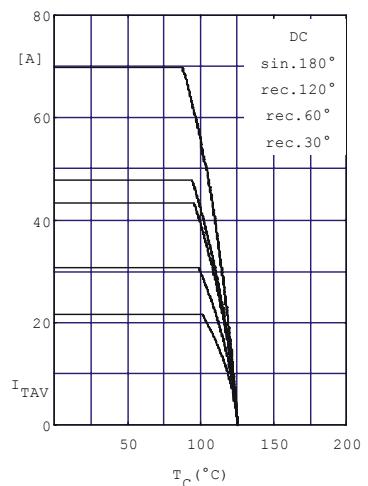


Fig.5 Maximum forward current at case temperature

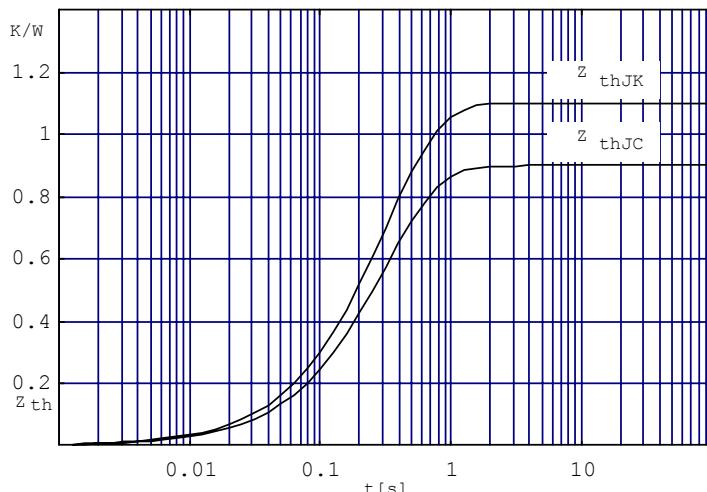


Fig.6 Transient thermal impedance per thyristor or diode

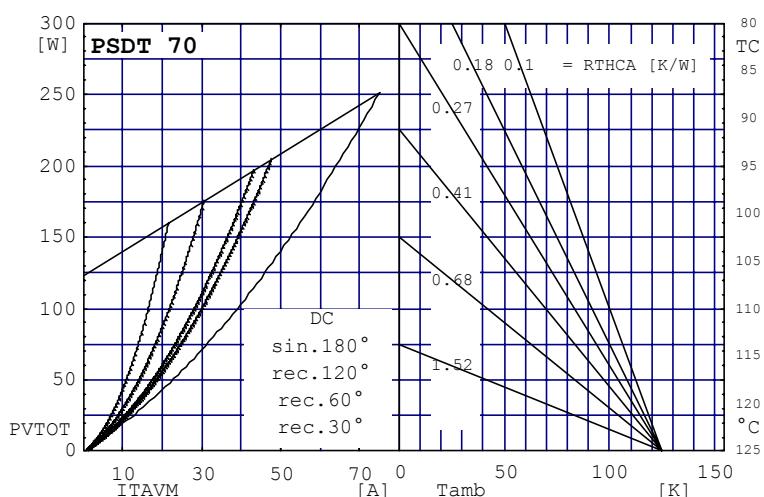


Fig. 7 Power dissipation vs. direct output current and ambient temperature